

SECOND PRELIMINARY AMENDMENT  
U.S. Appln. No. 09/787,139

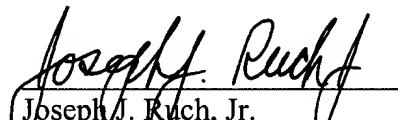
**REMARKS**

Claim 31 has been amended and new claim 47 has been added to place the claims in desired appropriate form for examination. Thus all of the claims are now in appropriate form, and the Examiner is respectfully requested to proceed with the examination.

Early favorable action is earnestly solicited.

In the event that the Examiner believes that it may facilitate the further prosecution of this application, the Examiner is invited to contact the undersigned attorney at the local Washington, D.C. telephone number indicated below.

Respectfully submitted,

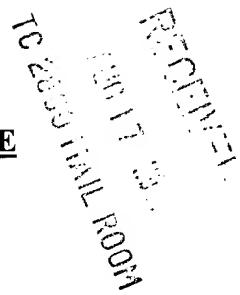


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**APPENDIX**

**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

**IN THE CLAIMS:**

**The claims are amended as follows:**

31. (amended) The process for manufacturing a multilayer printed circuit board according to ~~any of claims claim 27 to 30~~, wherein, in the step for thinning the copper foil of said copper-clad laminate by etching, the thickness of the copper foil is reduced to 1 to 10  $\mu\text{m}$ .

**Claim 47 is added as a new claim.**

47. (new) The process for manufacturing a multilayer printed circuit board according to claim 28, wherein, in the step for thinning the copper foil of said copper-clad laminate by etching, the thickness of the copper foil is reduced to 1 to 10  $\mu\text{m}$ .